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DIKE, BRONSTEIN, ROBERTS & CUSHMAN  
*Intellectual Property Practice Group*

MARLBOROUGH, MA OFFICE  
TELEPHONE (508) 485-7772

WASHINGTON, DC  
TELEPHONE (703) 553-2563

MAILING ADDRESS:  
P.O. BOX 9169  
BOSTON, MA 02209

101 FEDERAL STREET  
BOSTON, MA 02110  
(617) 439-4444  
FAX (617) 439-4170

2814

### FACSIMILE TRANSMITTAL

**DATE:** February 12, 2002

**TO:** U.S. Patent & Trademark Office  
Examining Group 2800

**FAX NO.:** 1-703-872-9318

**FROM:** Steven M. Jensen

**FAX NO.:** 617-439-4170

**Our Docket No.:** 55413 (71987)

**No. of Pages (incl. cover):** 5

**Re:** U.S. Serial Number 09/718,669

**MESSAGE:**

Please enter the attached Amendment.

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Docket No. 55413 (71987)

#5/a  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: P. Yuan et al.  
U.S.S.N.: 09/718,669 GROUP: 2814  
FILED: November 22, 2000 EXAMINER: D. Nguyen  
FOR: TAPE CARRIER PACKAGE STRUCTURE WITH DUMMY PADS  
AND DUMMY LEADS FOR PACKAGE REINFORCEMENT

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to Group 2800 of the U.S. Patent & Trademark Office by facsimile number 703-872-9318 on February 12, 2002.

By:

Steven M. Jensen

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated December 3, 2001 of the above-referenced application. Please amend the application as follows.

IN THE SPECIFICATION

On page 1, lines 25-26, please delete the paragraph.

On page 2, lines 11-14, please amend the paragraph as follows:

Referring further to FIG. 1C, in the next step, an encapsulation process is performed to dispense an encapsulation material, such as resin, through the gaps between the inner leads 130 into the device hole 120a so as to form an encapsulation body 140 to encapsulate the semiconductor chip 110.